

ABSTRACT

5 A heat conductive silicone composition comprising (a)
an organopolysiloxane having alkenyl groups only at both ends
of a molecular chain, (b) a heat conductive filler, (c) an
organohydrogenpolysiloxane having Si-H groups only at both
ends of a molecular chain, and (d) a platinum group curing
catalyst is shaped into an article which conforms to a member
10 and permits heat to dissipate from the member without
applying stresses thereto.